



# Product Change Notification - LIAL-25ZCPA706 (convert To PDF)

#### Date:

21 Mar 2018

#### **Product Category:**

8-bit PIC Microcontrollers

#### **Affected CPNs:**



## 

#### **Notification subject:**

CCB 3257 Initial Notice: Qualification of MTAI as an additional assembly site for selected Atmel products available in 8L SOIJ package.

#### Notification text:

#### **PCN Status:**

Initial notification.

## **PCN Type:**

Manufacturing Change

#### **Microchip Parts Affected:**

Please open one of the icons found on the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of MTAI as an additional assembly site for selected Atmel products available in 8L SOIJ package.

#### **Pre Change:**

Assembled in LPI using palladium coated copper wire with gold flash (CuPdAu) bond wire. CRM-1033BF die attach material

#### **Post Change:**

Assembled in LPI using palladium coated copper wire with gold flash (CuPdAu) bond wire, CRM-1033BF die attach material and assembled in MTAI using gold (Au) bond wire and 8390A die attach material

## **Pre and Post Change Summary:**

	Pre Change	Post Change				
Assembly Site	Lingsen Precision Industires, LTD. (LPI)	Lingsen Precision Industires, LTD. (LPI)	Microchip Technology Thailand HQ (MTAI)			
Wire material	CuPdAu	CuPdAu	Au			
Die attach material	CRM-1033BF	CRM- 1033BF	8390A			
Molding compound material	G600	G600	G600			
Lead frame material	C194	C194	C194			

### **Impacts to Data Sheet:**

None

## **Change Impact:**

None

#### **Reason for Change:**

To improve on-time delivery performance by qualifying MTAI as additional assembly site.

#### **Change Implementation Status:**

In Progress

## **Estimated Qualification Completion Date:**

April 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

#### **Time Table Summary:**

	February 2018					>	April 2018			
Workweek	06	07	08	09	10		14	15	16	17

Initial PCN Issue Date		X				
Qual Report Availability				X		
Final PCN Issue Date				Χ		

## **Method to Identify Change:**

Traceability code

#### **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

#### **Revision History:**

March 1, 2018: Issued initial notification.

**March 21, 2018**: Re-issued initial notification to update the post change and affected CPN list and to revised this initial notification to be issued to all affected customers.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):

PCN LIAL-25ZCPA706 QUAL PLAN.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

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